



# CY8C20142-SX1I

CY8C20142-SX1I	
Development Kit	CY3218-CAPEXP3
Automotive Qualified	N
CapSense	Y
Comm. Interface	I2C
Max. Operating Temp. (°C)	85
Max. Operating Voltage (V)	5.50
Min. Operating Temp. (°C)	-40
Min. Operating Voltage (V)	2.40
No. of CapSense IO	4
No. of Dedicated I2C	1
No. of Dedicated SPI	0
No. of GPIOs	4
No. of GPOs	N/A
No. of PWM Channels	0
PWMs	N
Proximity Sensing	N
Slider Segments	N/A
SmartSense Enabled	N
Tape & Reel	N

## PACKAGING/ORDERING

Package	SOIC
No. of Pins	8
Package Dimensions	193 L x 1.5 H x 150 W (Mils)
Package Weight	76.45 (mgs)
Package Cross Section Drawing	Download
Package Carrier	TUBE
Package Carrier Drawing / Orientation	Drawing
Standard Pack Quantity	485
Minimum Order Quantity (MOQ)	485
Order Increment	485
Estimated Lead Time (days)	91
HTS Code	8542.31.0001
ECCN	None
ECCN Suball	EAR99

## QUALITY AND ROHS

Moisture Sensitivity Level (MSL)	3
Peak Reflow Temp. (°C)	260 (Cypress Reflow Profile)
RoHS Compliant	Y Print RoHS Certificate of Compliance
PB Free	Y
Lead/Ball Finish	Ni/Pd/Au
Marking	Cypress Marking Format

### IPC 1752 Material Declaration

IPC1752 MATERIAL DECLARATION SOIC08 (SZ08)- AMKOR PHIL - AU WIRE *Last Update: Nov 10, 2016*

IPC1752 MATERIAL DECLARATION SOIC 08 (SZ08) - CML - AU WIRE *Last Update: Nov 10, 2016*

IPC1752 MATERIAL DECLARATION SOIC 08 (SZ08) - OSE - AU WIRE *Last Update: Nov 10, 2016*

### RoHS Analysis Certificates (CoA) for Direct Materials

Please click [here](#)

### Package Qualification Report

QTP 50701 8/14/16-Lead SOIC Package (150 mil) NiPdAu, MSL3 235C & 260C Reflow OSE-Taiwan (T).pdf *Last Update: Aug 07, 2015*

### Device Qualification Reports

FIT/MTBF, ESD (HBM/CDM) and Latch-up data available in the Device Qualification Report.

QTP 073803 PSOC (8C20100) IN S4AD-5 TECHNOLOGY AT FAB-4 CMI *Last Update: Sep 20, 2016*

QTP 090403: NANO PSOC 8C20100A (CAPSENSE VENUS) PRODUCT FAMILY S4AD-5 TECHNOLOGY, FAB5 QUALIFICATION REPORT *Last Update: Sep 17, 2016*